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## Enhancement of multi-layer stacking in micro-SD cards

### ~ Packaging ~

Size reduction and memory density increase are progressing in SD cards for storing large capacity information such as image data in portable electronic devices like mobile phones and digital cameras.

The SD card evolved into MiniSD and further MicroSD with smaller size and lighter weight. In order to realize this, a larger number of stacks and further thinning of the memory chips have been realized. The number of memory stacks progressed from 9 layers to 17, and further to 33 with a memory controller. Technologies to support this are wafer back grinding technology, thin wafer transfer technology, adhesive technology, and loop control wire bonding technology.



